

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

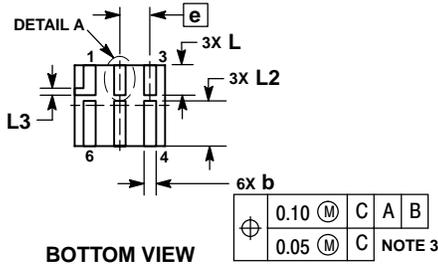
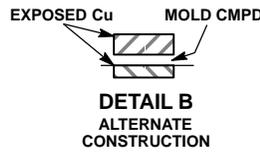
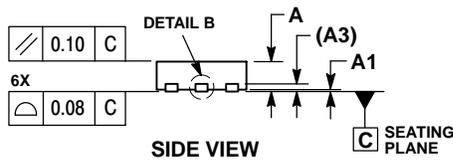
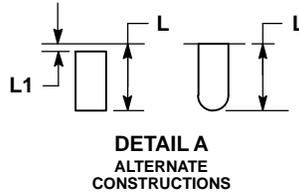
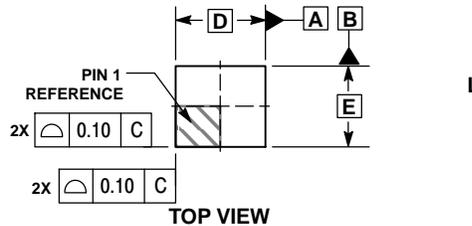
ON Semiconductor®



SCALE 4:1

XDFN6 1.50x1.35, 0.5P  
CASE 711AY  
ISSUE O

DATE 09 SEP 2014



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	1.50 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.35	0.55
L1	---	0.15
L2	0.65	0.85
L3	0.15 REF	

**GENERIC MARKING DIAGRAM\***

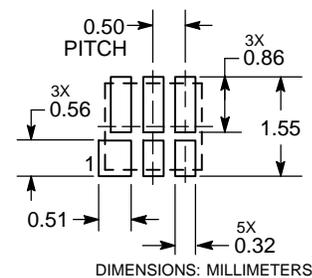


- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT**



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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	XDFN6 1.50X1.35, 0.5P	<b>PAGE 1 OF 2</b>

